

**AD6676 Assembly Bumping Site Transfer from Amkor to TSMC**

**Qualification Results Summary of 80-WLCSP  
Bumping to TSMC**

<b>QUALIFICATION PLAN / STATUS</b>			
<b>TEST</b>	<b>SPECIFICATION</b>	<b>SAMPLE SIZE</b>	<b>RESULTS</b>
High Temperature Operating Life (HTOL)	JEDEC <i>JESD22-A108</i>	<b>3*45</b> <b>6*32</b>	<b>Pass</b>
Highly Accelerated Stress Test (HAST)	JEDEC <i>JESD22-A110</i>	<b>9*32</b>	<b>Pass</b>
Temperature Cycle (TC)	JEDEC <i>JESD22-A104</i>	<b>9*45</b>	<b>Pass</b>
Temperature/Humidity/Bias (THB)	JEDEC <i>JESD22-A101</i>	<b>9*45</b>	<b>Pass</b>
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	<b>3*45</b>	<b>Pass</b>